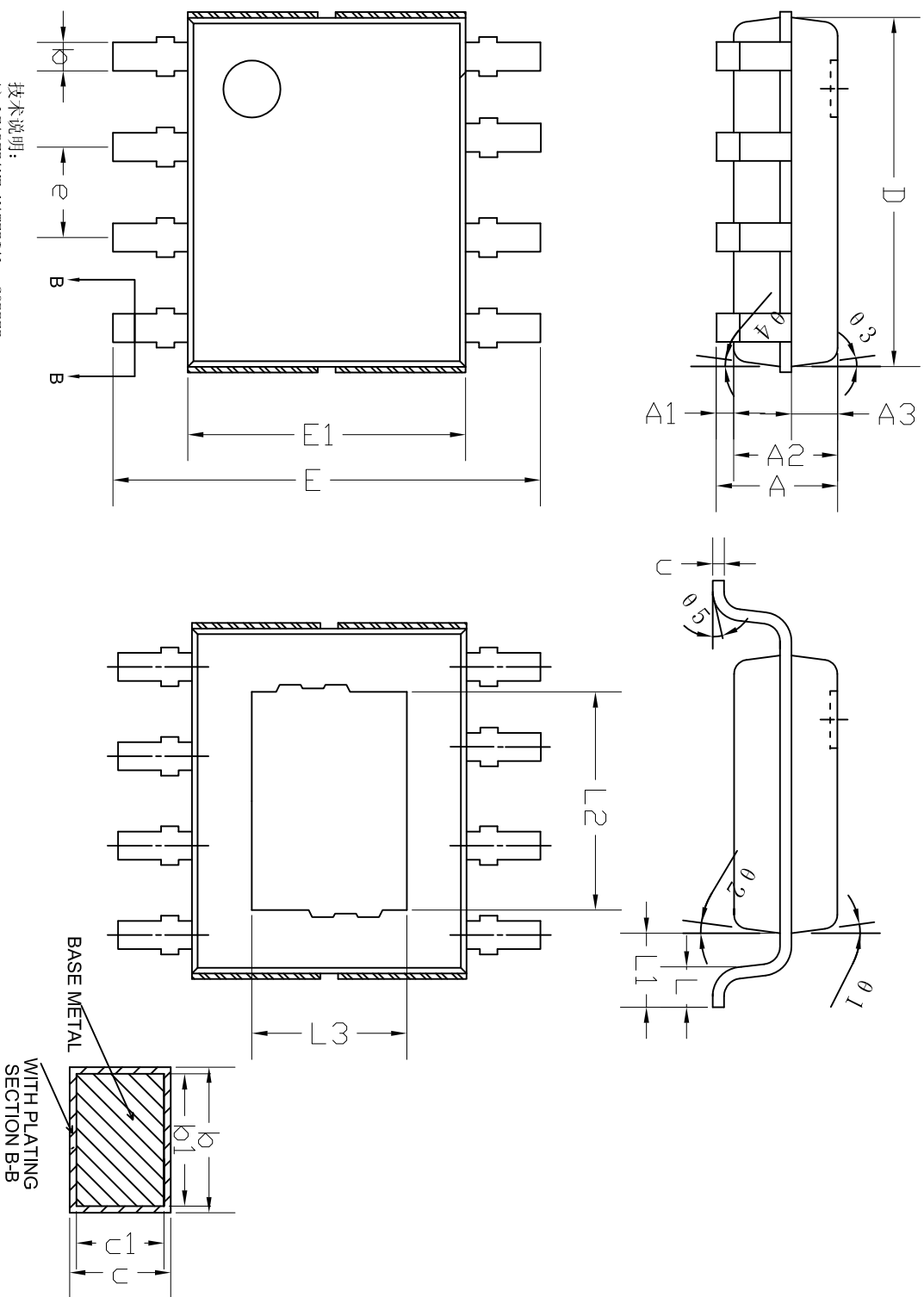


MARK	MARK	REVISION RECORD	REVISERE	APPROVER
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ESDP8 PACKAGE OUTLINE DIMENSIONS



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	--	--	1.65
A1	0.05	0.10	0.15
A2	1.40	1.42	1.50
A3	0.60	0.65	0.70
b	0.39	--	0.46
b1	0.38	0.41	0.44
c	0.20	--	0.24
c1	0.19	0.20	0.21
D	4.80	4.90	5.00
E	5.90	6.00	6.20
E1	3.85	3.90	4.00
e	1.27(BSC)		
L	0.50	0.60	0.70
L1	1.05(REF)		
L2	3.10(REF)		
L3	2.20(REF)		
theta1	6°	~	12°
theta2	6°	~	12°
theta3	5°	~	10°
theta4	5°	~	10°
phi	0°	~	6°

- 技术说明:
- 1) LEADFRAME MATERIAL: COPPER;
引线框架材料: 铜;
 - 2) LEADFRAME THICKNESS: 0.203mm;
引线框架厚度: 0.203mm;
 - 3) BOTH PACKAGE LENGTH AND WIDTH DO NOT INCLUDE MOLD FLASH;
塑封体长度及宽度尺寸不包括塑封溢胶;
 - 4) REFERENCE: JEDEC MS-013, MS-012.
参考标准: JEDEC MS-013, MS-012。